

Docket No. 2001.1531/24061.439  
Customer No.: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Chien-Chao Huang, et al.	§	Examiner:	TBD
Serial No.:	10/710,012	§	Art Unit:	2811
Filed:	June 11, 2004	§	Conf. No.:	4011
For:	Improved Cobalt Silicidation Process for Substrates with a Silicon Germanium Layer	§		

POWER OF ATTORNEY FOR PATENT APPLICATION

Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

As a representative of the Assignee, Taiwan Semiconductor Manufacturing, Co. Ltd., I hereby appoint the following attorneys to prosecute the above-identified application and to transact all business in the United States Patent and Trademark Office in connection therewith:

Practitioners associated with the Customer Number

42717

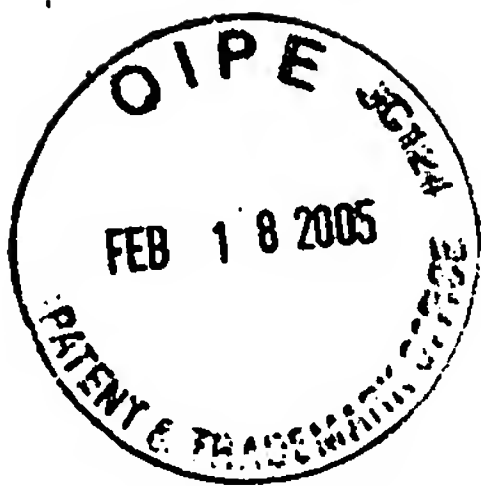
Please direct all correspondence and telephone calls to the address associated with the above-mentioned Customer Number.

The undersigned representative for the Assignee certifies that the assignee is the assignee of the entire right, title and interest in the above-identified patent application. A copy of the assignment or other documents in the chain of title are attached.

Executed the \_\_\_\_\_ day of \_\_\_\_\_, 2005.

Taiwan Semiconductor Manufacturing Company, Ltd.

Chien Wei Chou  
Director, IP Division



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CUSTOMER NO.: 42717

### ASSIGNMENT

WHEREAS, I,

- |     |                  |    |   |
|-----|------------------|----|---|
| (1) | Chien-Chao Huang | of | 6F-1, No. 32, Ti-Yu St.<br>Hsin-Chu City 300, Taiwan, R.O.C.  |
| (2) | Yee-Chia Yeo     | of | <del>Blk 684C Jiarong West St. 64, #05-131,<br/>No. 1, Lane 120, Ling-ya District</del> <i>S643684</i><br><del>Kaoshiung, Taiwan, R.O.C.</del> <i>Singapore.</i>      |
| (3) | Chao-Hsiung Wang | of | 3F-1, No. 178, Shanghei Rd.<br>Hsin-Chu, Taiwan 300, R.O.C.   |
| (4) | Chun-Chieh Lin   | of |   |
| (5) | Chenming Hu      | of | <del>60, Ming-Chung Rd</del> <i>260 Pebble Drive</i><br><del>Yun-Aian Li, Lu-Kang Jen</del> <i>Alamo, CA, 94507</i><br><del>Changhua, Taiwan, R.O.C.</del> <i>USA</i> |

have invented certain improvements in

### IMPROVED COBALT SILICIDATION PROCESS FOR SUBSTRATES WITH A SILICON GERMANIUM LAYER

for which I have executed an application for Letters Patent of the United States of America, filed on June 11, 2004 and assigned application number 10/710,012;

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under said invention and said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the invention, and said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

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AND I HEREBY further covenant and agree that I will communicate to TSMC, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor: Chien-Chao Huang

Dated: ✓ Chien-Chao Huang

✓ Feb. 14, 2005  
Inventor Signature

Inventor: Yee-Chia Yeo

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

Inventor: Chao-Hsiung Wang

Dated: ✓ Chao-Hsiung Wang

✓ Feb. 14, 2005  
Inventor Signature

Inventor: Chun-Chieh Lin

Dated: ✓ Chun-Chieh Lin

✓ Feb. 14, 2005  
Inventor Signature

Inventor: Chenming Hu

Dated: \_\_\_\_\_

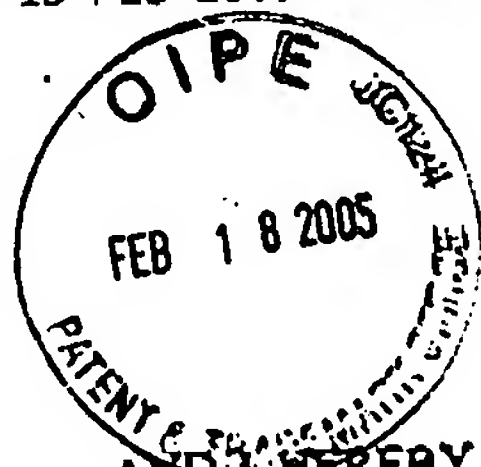
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Inventor Signature

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Inventor: Chien-Chao Huang

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

Inventor: Yee-Chia Yeo

Dated: ✓ 5th Feb. 2005.

✓ *Yee-Chia Yeo.*  
\_\_\_\_\_  
Inventor Signature

Inventor: Chao-Hsiung Wang

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

Inventor: Chun-Chieh Lin

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

Inventor: Chenming Hu

Dated: 2/14/2005

*Chenming Hu*  
\_\_\_\_\_  
Inventor Signature